



TECHNICAL DATA SHEET

1. PRODUCT NAME	REFERENCE	
Pumice	1.0	
2. MAIN INTENDED USE		
Recommended as a mild abrasive in glass treatments, electronic circuit board scrubbing, dental pastes & cosmetic exfoliants. Texturing additive in coatings and inks, lightweight filler in plasters and paints.		
3. CHEMICAL DESCRIPTION		
This media contains no free silica		
Compound/Element	Chemical Formula	Typical Content
Silicon Dioxide	SiO ₂	74.55%
Aluminium Oxide	Al ₂ O ₃	12.45%
Potassium Oxide	K ₂ O	4.50%
Sodium Oxide	Na ₂ O	4.00%
Ferric Oxide	Fe ₂ O	<2.00%
Calcium Oxide	CaO	<2.00%
Magnesium Oxide	MgO	<2.00%
Titanium Dioxide	TiO ₂	<2.00%
Sulphur Trioxide	SO ₃	0.20%
Manganese Oxide	MnO	0.10%
Carbon Dioxide	CO ₂	0.10%
Ferrous Oxide	FeO	0.06%
Phosphorous Pentoxide	P ₂ O ₅	0.005%
Combined Water	H ₂ O+	4.35%
Determined by FAAS		
4. PHYSICAL PROPERTIES	a. Bulk Density	0.67 g/cm ³
	b. Melting Point	1200 °C
	c. pH Value	7.0 – 8.0
	d. Specific Gravity	2.40 g/cm ³
	e. Hardness	5.5 Mohs
5. PARTICLE SIZE DISTRIBUTION	Microns	% Retained
	297	T - 5
	250	1 - 5
	177	5 - 15
	125	10 - 20
	88	10 - 20
	44	25 - 40
PAN	20 - 30	
6. PACKAGING		
Packed in 50lb (22.68kg) paper bags or 500kg IBC big bags.		

These results are based on analysis carried out on a representative sample of the relevant batch and do not release you from the obligation to test the product as to the suitability for its intended use.